

ALCOR - dRICH Readout

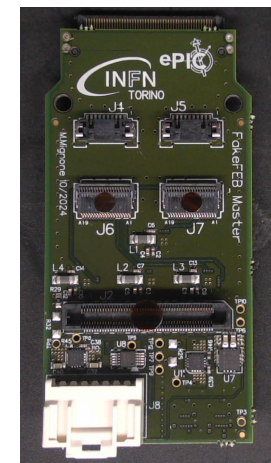
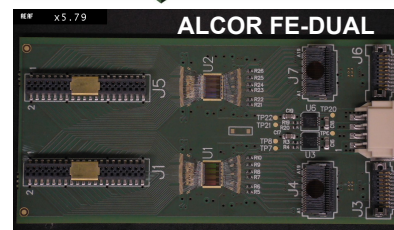
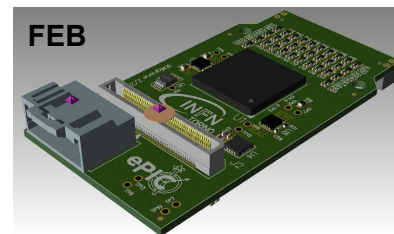
Fabio Cossio on behalf of the ALCOR group
INFN Torino

ePIC Electronics & DAQ WG meeting
ASICs & Electronics Monthly Progress Reports

02.10.2025

Summary of ALCOR activities

- **ALCORv3 (ALCOR-64)**
 - 64 channels, BGA package, shutter + other EIC-driven features
 - MPW tapeout on Apr 2025, 60 singulated dies received on Aug 26th
 - Packaging ongoing in Singapore, BGA devices to be received before end of 2025
- **dRICH ALCOR FEB**
 - Design completed in May, different versions towards final dRICH FEB: Fake, SMA, final
 - First samples available very soon
- **November beam test (CERN SPS)**
 - Will use old ALCORv2.1 boards coupled with new **RDO FPGA readout** using dedicated adapter (Fake-FEB)
 - Will increase number of PDUs (8→9), preparing new ALCORv2.1 FE-DUAL boards and spares



Fake-FEB